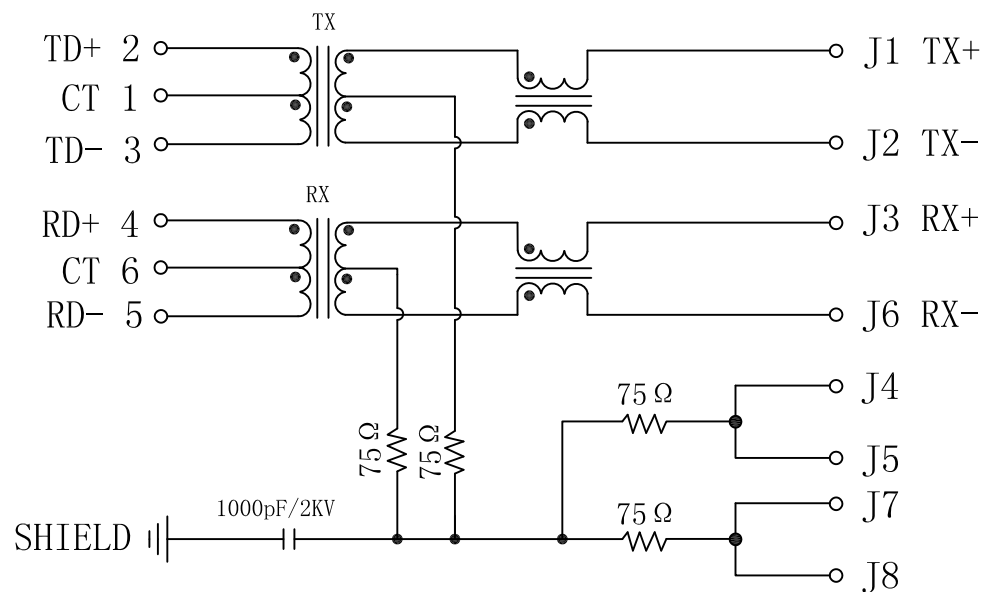


# Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
B	REL		2014-03-26	

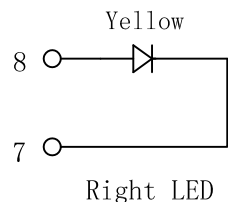
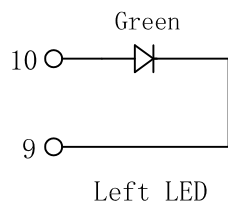
PC BOARD CONNECTIONS



RJ45 CONNECTOR

## ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio ( $\pm 3\%$ ):  
TX=1CT:1CT      RX=1CT:1CT
- Inductance OCL:  
350uH MIN @ 100KHz 0.1V 8mA DC Bias
- DCR:  
1.2  $\Omega$  MAX
- Insertion Loss:  
-1.0dB MAX @ 1-100MHz
- Return Loss:  
-18dB MIN @ 1-30MHz  
-15dB MIN @ 30-60MHz  
-12dB MIN @ 60-100MHz
- Cross talk:  
-40dB MIN @ 1-30MHz  
-35dB MIN @ 30-60MHz  
-30dB MIN @ 60-100MHz
- Common Mode Rejection:  
-30dB MIN @ 1-100MHz
- Hipot Test: 1500Vrms
- Operating Temperature Range: 0°C TO 70°C

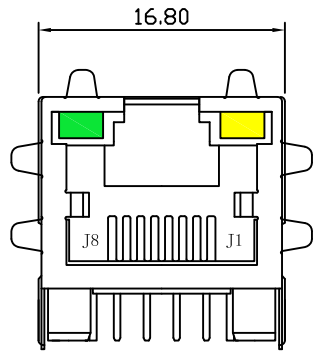


Emitting Color	$\lambda$ p(nm)	VF@IF=20mA	IR @VR=5V
Green	565	1.8~2.6V	10 $\mu$ A max
Yellow	585	1.8~2.6V	10 $\mu$ A max
Orange	610	1.8~2.6V	10 $\mu$ A max

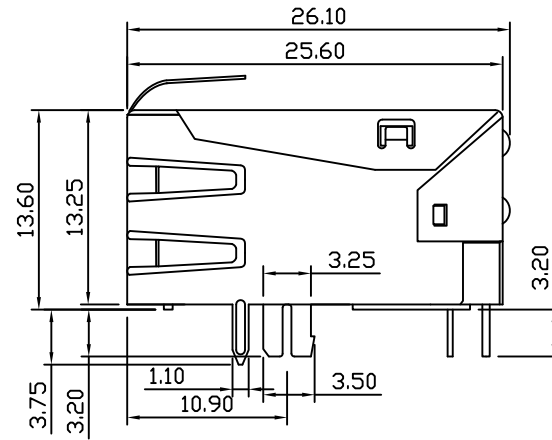
X:X	$\pm 0.25$	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	$\pm 0.20$	CHKD:	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
X:XXX	$\pm 0.05$	DR: TOM	PART NO.: LPJ2011KHNL	
ANGLES	$\pm 1^\circ$	UNIT: mm	DWG NO.: LP14032625	
	SCALE: 2/1	SHEET: 1/2	REV: B	

# Mechanical:

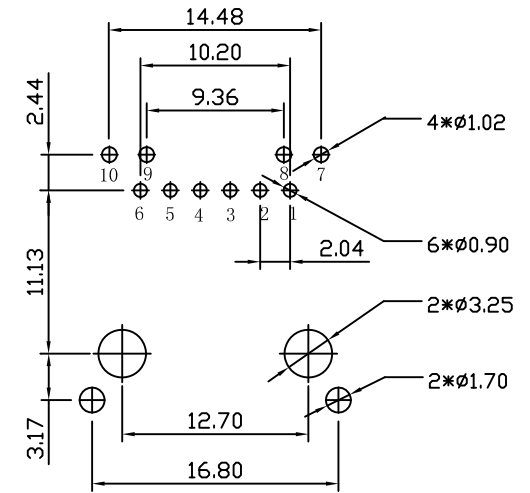
REV.	ECN NO.	DESCRIPTION	DATE	APPD
B	REL		2014-03-26	



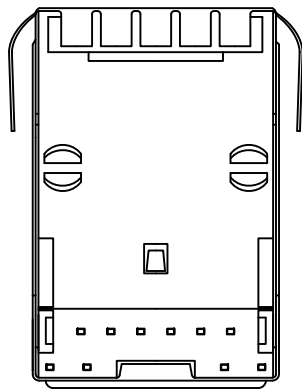
Front Side View



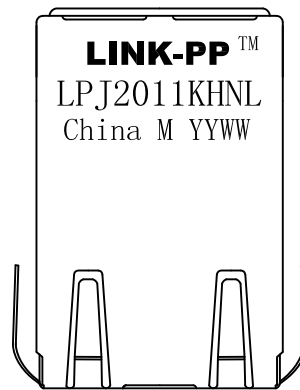
Left Side View



Suggested PCB Layout (Top View)



Bottom Side View



Top Side View

### NOTES:

1. Meets IEEE 802.3 specification
2. Connector Materials:  
 Housing Material: Thermoplastic PBT+30%G.F UL94V-0  
 Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm  
 Pins: Brass C2680R-H Thickness=0.35mm  
 Shield: SUS 201-1/2H Thickness=0.2mm  
 Contact plating: Gold 6 micro-inches min. In contact area.
3. Wave solder tip temperature: 265°C Max, 5 Sec Max



X:X ±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.20	CHKD:	
X:XXX ±0.05	DR: TOM	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics
ANGLES ±1°	UNIT: mm	PART NO.: LPJ2011KHNL
	SCALE: 2/1	SHEET: 2/2
	REV: B	DWG NO.: LP14032625